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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LVD, POR, PWM
Number of I/O	5
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.209", 5.30mm Width)
Supplier Device Package	8-SO
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mchc908qt4cdwe

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

General Description



RST, IRQ: Pins have internal (about 30K Ohms) pull up

PTA[0:5]: High current sink and source capability

PTA[0:5]: Pins have programmable keyboard interrupt and pull up

PTB[0:7]: Not available on 8-pin devices – MC68HC908QT1, MC68HC908QT2, and MC68HC908QT4 (see note in 12.1 Introduction)

ADC: Not available on the MC68HC908QY1 and MC68HC908QT1

Figure 1-1. Block Diagram



Chapter 2 Memory

2.1 Introduction

The central processor unit (CPU08) can address 64 Kbytes of memory space. The memory map, shown in Figure 2-1, includes:

- 4096 bytes of user FLASH for MC68HC908QT4 and MC68HC908QY4
- 1536 bytes of user FLASH for MC68HC908QT2, MC68HC908QT1, MC68HC908QY2, and MC68HC908QY1
- 128 bytes of random access memory (RAM)
- 48 bytes of user-defined vectors, located in FLASH
- 416 bytes of monitor read-only memory (ROM)
- 1536 bytes of FLASH program and erase routines, located in ROM

2.2 Unimplemented Memory Locations

Accessing an unimplemented location can have unpredictable effects on MCU operation. In Figure 2-1 and in register figures in this document, unimplemented locations are shaded.

2.3 Reserved Memory Locations

Accessing a reserved location can have unpredictable effects on MCU operation. In Figure 2-1 and in register figures in this document, reserved locations are marked with the word Reserved or with the letter R.



Memory

2.6.6 FLASH Block Protect Register

The FLASH block protect register is implemented as a byte within the FLASH memory, and therefore can only be written during a programming sequence of the FLASH memory. The value in this register determines the starting address of the protected range within the FLASH memory.



Write to this register is by a programming sequence to the FLASH memory.

Figure 2-5. FLASH Block Protect Register (FLBPR)

BPR[7:0] — FLASH Protection Register Bits [7:0]

These eight bits in FLBPR represent bits [13:6] of a 16-bit memory address. Bits [15:14] are 1s and bits [5:0] are 0s.

The resultant 16-bit address is used for specifying the start address of the FLASH memory for block protection. The FLASH is protected from this start address to the end of FLASH memory, at \$FFFF. With this mechanism, the protect start address can be XX00, XX40, XX80, or XXC0 within the FLASH memory. See Figure 2-6 and Table 2-2.



Figure 2-6. FLASH Block Protect Start Address

BPR[7:0]	Start of Address of Protect Range				
\$00 - \$B8	The entire FLASH memory is protected.				
\$B9 (1011 1001)	\$EE40 (11 10 1110 01 00 0000)				
\$BA (1011 1010)	\$EE80 (11 10 1110 10 00 0000)				
\$BB (1011 1011)	\$EEC0 (11 10 1110 11 00 0000)				
\$BC (1011 1100)	\$EF00 (11 10 1111 00 00 0000)				
and so on					
\$DE (1101 1110)	\$F780 (11 11 0111 10 00 0000)				
\$DF (1101 1111)	\$F7C0 (11 11 0111 11 00 0000)				
\$FE (1111 1110)	\$FF80 (11 11 1111 10 00 0000) FLBPR, internal oscillator trim values, and vectors are protecte				
\$FF	The entire FLASH memory is not protected.				

Table 2-2. Examples of Protect Start Address



Chapter 3 Analog-to-Digital Converter (ADC)

3.1 Introduction

This section describes the analog-to-digital converter (ADC). The ADC is an 8-bit, 4-channel analog-todigital converter. The ADC module is only available on the MC68HC908QY2, MC68HC908QT2, MC68HC908QY4, and MC68HC908QT4.

3.2 Features

Features of the ADC module include:

- 4 channels with multiplexed input
- · Linear successive approximation with monotonicity
- 8-bit resolution
- Single or continuous conversion
- Conversion complete flag or conversion complete interrupt
- Selectable ADC clock frequency

3.3 Functional Description

Four ADC channels are available for sampling external sources at pins PTA0, PTA1, PTA4, and PTA5. An analog multiplexer allows the single ADC converter to select one of the four ADC channels as an ADC voltage input (ADCVIN). ADCVIN is converted by the successive approximation register-based counters. The ADC resolution is eight bits. When the conversion is completed, ADC puts the result in the ADC data register and sets a flag or generates an interrupt.

Figure 3-2 shows a block diagram of the ADC.

3.3.1 ADC Port I/O Pins

PTA0, PTA1, PTA4, and PTA5 are general-purpose I/O pins that are shared with the ADC channels. The channel select bits (ADC status and control register (ADSCR), \$003C), define which ADC channel/port pin will be used as the input signal. The ADC overrides the port I/O logic by forcing that pin as input to the ADC. The remaining ADC channels/port pins are controlled by the port I/O logic and can be used as general-purpose I/O. Writes to the port register or data direction register (DDR) will not have any affect on the port pin that is selected by the ADC. Read of a port pin which is in use by the ADC will return a 0 if the corresponding DDR bit is at 0. If the DDR bit is at 1, the value in the port data latch is read.



Analog-to-Digital Converter (ADC)

3.3.2 Voltage Conversion

When the input voltage to the ADC equals V_{DD} , the ADC converts the signal to \$FF (full scale). If the input voltage equals V_{SS} , the ADC converts it to \$00. Input voltages between V_{DD} and V_{SS} are a straight-line linear conversion. All other input voltages will result in \$FF if greater than V_{DD} and \$00 if less than V_{SS} .

NOTE

Input voltage should not exceed the analog supply voltages.

3.3.3 Conversion Time

Sixteen ADC internal clocks are required to perform one conversion. The ADC starts a conversion on the first rising edge of the ADC internal clock immediately following a write to the ADSCR. If the ADC internal clock is selected to run at 1 MHz, then one conversion will take 16 μ s to complete. With a 1-MHz ADC internal clock the maximum sample rate is 62.5 kHz.

Conversion Time = $\frac{16 \text{ ADC Clock Cycles}}{\text{ADC Clock Frequency}}$

Number of Bus Cycles = Conversion Time \times Bus Frequency

3.3.4 Continuous Conversion

In the continuous conversion mode (ADCO = 1), the ADC continuously converts the selected channel filling the ADC data register (ADR) with new data after each conversion. Data from the previous conversion will be overwritten whether that data has been read or not. Conversions will continue until the ADCO bit is cleared. The COCO bit (ADSCR, \$003C) is set after each conversion and will stay set until the next read of the ADC data register.

When a conversion is in process and the ADSCR is written, the current conversion data should be discarded to prevent an incorrect reading.

3.3.5 Accuracy and Precision

The conversion process is monotonic and has no missing codes.

3.4 Interrupts

When the AIEN bit is set, the ADC module is capable of generating a central processor unit (CPU) interrupt after each ADC conversion. A CPU interrupt is generated if the COCO bit is at 0. The COCO bit is not used as a conversion complete flag when interrupts are enabled.

3.5 Low-Power Modes

The following subsections describe the ADC in low-power modes.

3.5.1 Wait Mode

The ADC continues normal operation during wait mode. Any enabled CPU interrupt request from the ADC can bring the microcontroller unit (MCU) out of wait mode. If the ADC is not required to bring the MCU out of wait mode, power down the ADC by setting the CH[4:0] bits in ADSCR to 1s before executing the WAIT instruction.



Auto Wakeup Module (AWU)



Figure 4-1. Auto Wakeup Interrupt Request Generation Logic

The auto wakeup RC oscillator is highly dependent on operating voltage and temperature. This feature is not recommended for use as a time-keeping function.

The wakeup request is latched to allow the interrupt source identification. The latched value, AWUL, can be read directly from the bit 6 position of PTA data register. This is a read-only bit which is occupying an empty bit position on PTA. No PTA associated registers, such as PTA6 data, PTA6 direction, and PTA6 pullup exist for this bit. The latch can be cleared by writing to the ACKK bit in the KBSCR register. Reset also clears the latch. AWUIE bit in KBI interrupt enable register (see Figure 4-1) has no effect on AWUL reading.

The AWU oscillator and counters are inactive in normal operating mode and become active only upon entering stop mode.

4.4 Wait Mode

The AWU module remains inactive in wait mode.

4.5 Stop Mode

When the AWU module is enabled (AWUIE = 1 in the keyboard interrupt enable register) it is activated automatically upon entering stop mode. Clearing the IMASKK bit in the keyboard status and control register enables keyboard interrupt requests to bring the MCU out of stop mode. The AWU counters start from '0' each time stop mode is entered.



Configuration Register (CONFIG)



Computer Operating Properly (COP)



External Interrupt (IRQ)



RST, IRQ: Pins have internal (about 30K Ohms) pull up

PTA[0:5]: High current sink and source capability

PTA[0:5]: Pins have programmable keyboard interrupt and pull up

PTB[0:7]: Not available on 8-pin devices – MC68HC908QT1, MC68HC908QT2, and MC68HC908QT4 (see note in 12.1 Introduction)

ADC: Not available on the MC68HC908QY1 and MC68HC908QT1

Figure 8-1. Block Diagram Highlighting IRQ Block and Pins

When set, the IMASK bit in INTSCR masks the IRQ interrupt request. A latched interrupt request is not presented to the interrupt priority logic unless IMASK is clear.

NOTE

The interrupt mask (I) in the condition code register (CCR) masks all interrupt requests, including the \overline{IRQ} interrupt request.

A falling edge on the IRQ pin can latch an interrupt request into the IRQ latch. An IRQ vector fetch, software clear, or reset clears the IRQ latch.



External Interrupt (IRQ)



Keyboard Interrupt Module (KBI)

To determine the logic level on a keyboard interrupt pin, use the data direction register to configure the pin as an input and then read the data register.

NOTE

Setting a keyboard interrupt enable bit (KBIEx) forces the corresponding keyboard interrupt pin to be an input, overriding the data direction register. However, the data direction register bit must be a 0 for software to read the pin.

9.3.2 Keyboard Initialization

When a keyboard interrupt pin is enabled, it takes time for the internal pullup to reach a logic 1. Therefore a false interrupt can occur as soon as the pin is enabled.

To prevent a false interrupt on keyboard initialization:

- 1. Mask keyboard interrupts by setting the IMASKK bit in the keyboard status and control register.
- 2. Enable the KBI pins by setting the appropriate KBIEx bits in the keyboard interrupt enable register.
- 3. Write to the ACKK bit in the keyboard status and control register to clear any false interrupts.
- 4. Clear the IMASKK bit.

An interrupt signal on an edge-triggered pin can be acknowledged immediately after enabling the pin. An interrupt signal on an edge- and level-triggered interrupt pin must be acknowledged after a delay that depends on the external load.

Another way to avoid a false interrupt:

- 1. Configure the keyboard pins as outputs by setting the appropriate DDRA bits in the data direction register A.
- 2. Write 1s to the appropriate port A data register bits.
- 3. Enable the KBI pins by setting the appropriate KBIEx bits in the keyboard interrupt enable register.

9.4 Wait Mode

The keyboard module remains active in wait mode. Clearing the IMASKK bit in the keyboard status and control register enables keyboard interrupt requests to bring the MCU out of wait mode.

9.5 Stop Mode

The keyboard module remains active in stop mode. Clearing the IMASKK bit in the keyboard status and control register enables keyboard interrupt requests to bring the MCU out of stop mode.

9.6 Keyboard Module During Break Interrupts

The system integration module (SIM) controls whether the keyboard interrupt latch can be cleared during the break state. The BCFE bit in the break flag control register (BFCR) enables software to clear status bits during the break state.

To allow software to clear the keyboard interrupt latch during a break interrupt, write a 1 to the BCFE bit. If a latch is cleared during the break state, it remains cleared when the MCU exits the break state.



again in the SIM and results in the internal bus frequency being one fourth of either the XTALCLK, RCCLK, or INTCLK frequency.

11.5 Low Power Modes

The WAIT and STOP instructions put the MCU in low-power consumption standby modes.

11.5.1 Wait Mode

The WAIT instruction has no effect on the oscillator logic. BUSCLKX2 and BUSCLKX4 continue to drive to the SIM module.

11.5.2 Stop Mode

The STOP instruction disables either the XTALCLK, the RCCLK, or INTCLK output, hence BUSCLKX2 and BUSCLKX4.

11.6 Oscillator During Break Mode

The oscillator continues to drive BUSCLKX2 and BUSCLKX4 when the device enters the break state.

11.7 CONFIG2 Options

Two CONFIG2 register options affect the operation of the oscillator module: OSCOPT1 and OSCOPT0. All CONFIG2 register bits will have a default configuration. Refer to Chapter 5 Configuration Register (CONFIG) for more information on how the CONFIG2 register is used.

Table 11-2 shows how the OSCOPT bits are used to select the oscillator clock source.

 Table 11-2. Oscillator Modes

OSCOPT1	OSCOPT0	Oscillator Modes
0	0	Internal oscillator
0	1	External oscillator
1	0	External RC
1	1	External crystal

11.8 Input/Output (I/O) Registers

The oscillator module contains these two registers:

- 1. Oscillator status register (OSCSTAT)
- 2. Oscillator trim register (OSCTRIM)



Figure 12-3 shows the port A I/O logic.



Figure 12-3. Port A I/O Circuit

NOTE Figure 12-3 does not apply to PTA2

When DDRAx is a 1, reading address \$0000 reads the PTAx data latch. When DDRAx is a 0, reading address \$0000 reads the voltage level on the pin. The data latch can always be written, regardless of the state of its data direction bit.

12.2.3 Port A Input Pullup Enable Register

The port A input pullup enable register (PTAPUE) contains a software configurable pullup device for each if the six port A pins. Each bit is individually configurable and requires the corresponding data direction register, DDRAx, to be configured as input. Each pullup device is automatically and dynamically disabled when its corresponding DDRAx bit is configured as output.





OSC2EN — Enable PTA4 on OSC2 Pin

This read/write bit configures the OSC2 pin function when internal oscillator or RC oscillator option is selected. This bit has no effect for the XTAL or external oscillator options.

1 = OSC2 pin outputs the internal or RC oscillator clock (BUSCLKX4)

0 = OSC2 pin configured for PTA4 I/O, having all the interrupt and pullup functions





Figure 13-2. SIM Clock Signals

13.3.1 Bus Timing

In user mode, the internal bus frequency is the oscillator frequency (BUSCLKX4) divided by four.

13.3.2 Clock Start-Up from POR

When the power-on reset module generates a reset, the clocks to the CPU and peripherals are inactive and held in an inactive phase until after the 4096 BUSCLKX4 cycle POR time out has completed. The IBUS clocks start upon completion of the time out.

13.3.3 Clocks in Stop Mode and Wait Mode

Upon exit from stop mode by an interrupt or reset, the SIM allows BUSCLKX4 to clock the SIM counter. The CPU and peripheral clocks do not become active until after the stop delay time out. This time out is selectable as 4096 or 32 BUSCLKX4 cycles. See 13.7.2 Stop Mode.

In wait mode, the CPU clocks are inactive. The SIM also produces two sets of clocks for other modules. Refer to the wait mode subsection of each module to see if the module is active or inactive in wait mode. Some modules can be programmed to be active in wait mode.

13.4 Reset and System Initialization

The MCU has these reset sources:

- Power-on reset module (POR)
- External reset pin (RST)
- Computer operating properly module (COP)
- Low-voltage inhibit module (LVI)
- Illegal opcode
- Illegal address

All of these resets produce the vector \$FFFE_FFF (\$FEFE_FEFF in monitor mode) and assert the internal reset signal (IRST). IRST causes all registers to be returned to their default values and all modules to be returned to their reset states.

An internal reset clears the SIM counter (see 13.5 SIM Counter), but an external reset does not. Each of the resets sets a corresponding bit in the SIM reset status register (SRSR). See 13.8 SIM Registers.



Development Support

15.2.2.5 Break Flag Control Register

The break control register (BFCR) contains a bit that enables software to clear status bits while the MCU is in a break state.



Figure 15-8. Break Flag Control Register (BFCR)

BCFE — Break Clear Flag Enable Bit

This read/write bit enables software to clear status bits by accessing status registers while the MCU is in a break state. To clear status bits during the break state, the BCFE bit must be set.

- 1 = Status bits clearable during break
- 0 = Status bits not clearable during break

15.2.3 Low-Power Modes

The WAIT and STOP instructions put the MCU in low power- consumption standby modes. If enabled, the break module will remain enabled in wait and stop modes. However, since the internal address bus does not increment in these modes, a break interrupt will never be triggered.

15.3 Monitor Module (MON)

This subsection describes the monitor module (MON) and the monitor mode entry methods. The monitor allows debugging and programming of the microcontroller unit (MCU) through a single-wire interface with a host computer. Monitor mode entry can be achieved without use of the higher test voltage, V_{TST} , as long as vector addresses \$FFFE and \$FFFF are blank, thus reducing the hardware requirements for in-circuit programming.

Features include:

- Normal user-mode pin functionality on most pins
- One pin dedicated to serial communication between MCU and host computer
- Standard non-return-to-zero (NRZ) communication with host computer
- Execution of code in random-access memory (RAM) or FLASH
- FLASH memory security feature⁽¹⁾
- FLASH memory programming interface
- Use of external 9.8304 MHz oscillator to generate internal frequency of 2.4576 MHz
- Simple internal oscillator mode of operation (no external clock or high voltage)
- Monitor mode entry without high voltage, V_{TST}, if reset vector is blank (\$FFFE and \$FFFF contain \$FF)
- Standard monitor mode entry if high voltage is applied to IRQ

^{1.} No security feature is absolutely secure. However, Freescale's strategy is to make reading or copying the FLASH difficult for unauthorized users.





Figure 15-10. Monitor Mode Circuit (External Clock, with High Voltage)



Figure 15-11. Monitor Mode Circuit (External Clock, No High Voltage)

MC68HC908QY/QT Family Data Sheet, Rev. 6



16.7 5-V Control Timing

Characteristic ⁽¹⁾	Symbol	Min	Max	Unit
Internal operating frequency	f _{OP} (f _{Bus})		8	MHz
Internal clock period (1/f _{OP})	t _{cyc}	125		ns
RST input pulse width low	t _{RL}	100		ns
IRQ interrupt pulse width low (edge-triggered)	t _{ILIH}	100	_	ns
IRQ interrupt pulse period	t _{ILIL}	Note ⁽²⁾	—	t _{cyc}

1. V_{DD} = 4.5 to 5.5 Vdc, V_{SS} = 0 Vdc, T_A = T_L to T_H; timing shown with respect to 20% V_{DD} and 70% V_{SS}, unless otherwise noted.

2. The minimum period is the number of cycles it takes to execute the interrupt service routine plus 1 t_{cyc} .





16.14 Analog-to-Digital Converter Characteristics

Characteristic	Symbol	Min	Max	Unit	Comments
Supply voltage	V _{DDAD}	2.7 (V _{DD} min)	5.5 (V _{DD} max)	V	_
Input voltages	V _{ADIN}	V _{SS}	V _{DD}	V	—
Resolution (1 LSB)	RES	10.5	21.5	mV	—
Absolute accuracy (Total unadjusted error)	E _{TUE}	_	± 1.5	LSB	Includes quantization
ADC internal clock	f _{ADIC}	0.5	1.048	MHz	$t_{ADIC} = 1/f_{ADIC},$ tested only at 1 MHz
Conversion range	V _{AIN}	V _{SS}	V _{DD}	V	—
Power-up time	t _{ADPU}	16	—	t _{ADIC} cycles	$t_{ADIC} = 1/f_{ADIC}$
Conversion time	t _{ADC}	16	17	t _{ADIC} cycles	$t_{ADIC} = 1/f_{ADIC}$
Sample time ⁽¹⁾	t _{ADS}	5	—	t _{ADIC} cycles	$t_{ADIC} = 1/f_{ADIC}$
Zero input reading ⁽²⁾	Z _{ADI}	00	01	Hex	$V_{IN} = V_{SS}$
Full-scale reading ⁽³⁾	F _{ADI}	FE	FF	Hex	$V_{IN} = V_{DD}$
Input capacitance	C _{ADI}	—	8	pF	Not tested
Input leakage ⁽³⁾	IIL	—	± 1	μA	—
ADC supply current $V_{DD} = 3 V$ $V_{DD} = 5 V$	I _{ADAD}	Туріса Туріса	l = 0.45 l = 0.65	mA mA	Enabled Enabled

1. Source impedances greater than 10 kΩ adversely affect internal RC charging time during input sampling.

2. Zero-input/full-scale reading requires sufficient decoupling measures for accurate conversions.

3. The external system error caused by input leakage current is approximately equal to the product of R source and input current.



Chapter 17 Ordering Information and Mechanical Specifications

17.1 Introduction

This section contains order numbers for the MC68HC908QY1, MC68HC908QY2, MC68HC908QY4, MC68HC908QT1, MC68HC908QT2, and MC69HC908QT4. Dimensions are given for:

- 8-pin plastic dual in-line package (PDIP)
- 8-pin small outline integrated circuit (SOIC) package
- 8-pin dual flat no lead (DFN) package
- 16-pin PDIP
- 16-pin SOIC
- 16-pin thin shrink small outline package (TSSOP)

17.2 MC Order Numbers

	4.5.0		Data
MC Order Number	ADC	FLASH Memory	Раскаде
MC908QY1	—	1536 bytes	16-pins
MC908QY2	Yes	1536 bytes	PDIP, SOIC,
MC908QY4	Yes	4096 bytes	and TSSOP
MC908QT1	—	1536 bytes	8-pins
MC908QT2	Yes	1536 bytes	PDIP, SOIC,
MC908QT4	Yes	4096 bytes	and DFN

 Table 17-1. MC Order Numbers

Temperature and package designators:

$$C = -40 \bullet C$$
 to $+85 \bullet C$

 $V = -40 \cdot C \text{ to } +105 \cdot C$

 $M = -40 \cdot C \text{ to } + 125 \cdot C$

P = Plastic dual in-line package (PDIP)

DW = Small outline integrated circuit package (SOIC)

DT = Thin shrink small outline package (TSSOP)

FQ = Dual flat no lead (DFN)



Figure 17-1. Device Numbering System

17.3 Package Dimensions

Refer to the following pages for detailed package dimensions.

